

Europe Flip Chip Market By Packaging Technology (2.5D IC, 3D IC, and 2D IC), By Bumping Technology (Copper Pillar, Gold Bumping, Solder Bumping and Others), By End User (Electronics, Industrial, IT & Telecom, Automotive, Healthcare & Life Sciences, Aerospace & Defense and Others), By Country, Industry Analysis and Forecast, 2020 - 2026

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Abstracts

The Europe Flip Chip Market would witness market growth of 8% CAGR during the forecast period (2020-2026).

Flip chips deliver a wide variety of benefits relative to wire bond packaging, such as substrate durability, superior physical and thermal and electrical efficiency, fast speed and reliability. Recent advanced flip-chip prototypes are in development with as many as 5,908 bumps/chip at a pitch of 200- μ m and 1,500 bumps / chip at a pitch of 170- μ m in the area array configurations.

One of the reasons that has a significant effect on demand for flip technology is the strong availability of devices such as smartphones, smart warbles, laptops and other portable products. Flip chip technology is being used to develop current products, and flip chip market manufacturers are already investing in R&D to implement form factors in different ranges. For example, manufacturers such as Intel and Samsung electronics have made a series of promotions to reduce the form factor for portable devices.

Nevertheless, the high costs associated with the introduction of flip-chip technology and the existence of low customization options compared to wire bonding are expected to impede market growth to a large extent. The continuously declining size of digital

devices and the growing demand for mobile sensors are anticipated to be key trends in the flip-chip market during the forecast period.

Based on Packaging Technology, the market is segmented into 2.5D IC, 3D IC and 2D IC. Based on Bumping Technology, the market is segmented into Copper Pillar, Gold Bumping, Solder Bumping and Others. Based on End User, the market is segmented into Electronics, Industrial, IT & Telecom, Automotive, Healthcare & Life Sciences, Aerospace & Defense and Others. Based on countries, the market is segmented into Germany, UK, France, Russia, Spain, Italy, and Rest of Europe.

The market research report covers the analysis of key stake holders of the market. Key companies profiled in the report include 3M Company, Advanced Micro Devices, Inc., Amkor Technology, Inc., Apple, Inc., Fujitsu Limited, Intel Corporation, IBM Corporation, Samsung Electronics Co., Ltd., Texas Instruments, Inc., and Taiwan Semiconductor Manufacturing Company.

Scope of the Study

Market Segmentation:

By Packaging Technology

2.5D IC

3D IC

2D IC

By Bumping Technology

Copper Pillar

Gold Bumping

Solder Bumping

Others

By End User

Electronics

Industrial

IT & Telecom

Automotive

Healthcare & Life Sciences

Aerospace & Defense

Others

By Country

Germany

UK

France

Russia

Spain

Italy

Rest of Europe

Companies Profiled

3M Company

Advanced Micro Devices, Inc.

Amkor Technology, Inc.

Apple, Inc.

Fujitsu Limited

Intel Corporation

IBM Corporation

Samsung Electronics Co., Ltd.

Texas Instruments, Inc.

Taiwan Semiconductor Manufacturing Company

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